

L Number	Hits	Search Text	DB	Time stamp
4	2766	corrugated and substrate and light	USPAT; EPO; JPO	2004/06/28 08:21
5	278	257/95.ccls.	USPAT; EPO; JPO	2004/06/28 08:21
6	1445	257/98.ccls.	USPAT; EPO; JPO	2004/06/28 08:21
1	179	313/\$.ccls. and corrugated	USPAT; EPO; JPO	2004/06/28 08:21
2	47	313/\$.ccls. and corrugated and substrate	USPAT; EPO; JPO	2004/06/28 08:21
11	920	313/504.ccls.	USPAT; EPO; JPO	2004/06/28 08:21
3	1153	313/506.ccls.	USPAT; EPO; JPO	2004/06/28 08:21
12	296	313/498.ccls.	USPAT; EPO; JPO	2004/06/28 08:21
7	218	corrugated and substrate and "light emitting"	USPAT; EPO; JPO	2004/06/28 08:22
8	7	313/506.ccls. and (texture)	USPAT; EPO; JPO	2004/06/28 08:22
9	4	313/506.ccls. and (textured)	USPAT; EPO; JPO	2004/06/28 08:22
10	88	313/506.ccls. and (uneven)	USPAT; EPO; JPO	2004/06/28 08:22
13	1188	(IWATA near1 HIROSHI).in.	USPAT; EPO; JPO	2004/06/28 08:22
14	303	(IWATA near1 HIROSHI).in. and semiconductor	USPAT; EPO; JPO	2004/06/28 08:22